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Examiner Name	

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Examiner's Initials*	Cite No. (optional)	OTHER DOCUMENTS
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EXAMINER SIGNATURE:	/Phung Chung/	DATE CONSIDERED:	05/18/2006

* Examiner: Initial if reference considered, whether or not in conformance with MPEP 609. Draw line through cite if not in conformance and not considered. Include copy of this form with next communication to applicant.